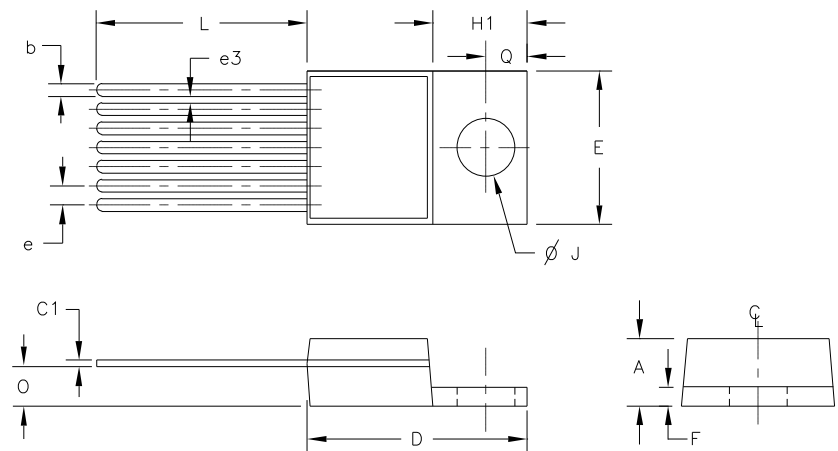


Package Number 336 - TO220, 7-Lead



DIM	INCHES		MILLIMETERS		NOM E	DIM	INCHES		MILLIMETERS		NOM E
	MIN.	MAX.	MIN.	MAX.			MIN.	MAX.	MIN.	MAX.	
A	.169	.185	4.29	4.70							
b	.026	.036	0.66	0.91							
C1	.016	.022	0.41	0.56							
D	.560	.590	14.22	14.99							
E	.390	.410	9.91	10.41							
e	.045	.055	1.14	1.40							
e3	.014	.024	0.36	0.61							
F	.045	.055	1.14	1.40							
H1	.235	.258	5.97	6.55							
J	.147	.155	3.73	3.94							
Q	.103	.113	2.62	2.87							
L	.540	.560	13.72	14.22							
O	.090	.115	2.29	2.92							

NOTES:

PACKAGE NUMBER: ZZ336	REV.: A
JEDEC NUMBER: NONE	



IMPORTANT NOTICE

Texas Instruments and its subsidiaries (TI) reserve the right to make changes to their products or to discontinue any product or service without notice, and advise customers to obtain the latest version of relevant information to verify, before placing orders, that information being relied on is current and complete. All products are sold subject to the terms and conditions of sale supplied at the time of order acknowledgment, including those pertaining to warranty, patent infringement, and limitation of liability.

TI warrants performance of its semiconductor products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are utilized to the extent TI deems necessary to support this warranty. Specific testing of all parameters of each device is not necessarily performed, except those mandated by government requirements.

Customers are responsible for their applications using TI components.

In order to minimize risks associated with the customer's applications, adequate design and operating safeguards must be provided by the customer to minimize inherent or procedural hazards.

TI assumes no liability for applications assistance or customer product design. TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right of TI covering or relating to any combination, machine, or process in which such semiconductor products or services might be or are used. TI's publication of information regarding any third party's products or services does not constitute TI's approval, warranty or endorsement thereof.